

TGP3500PT, TGP6000PT and TGP8000PT

Thermally Conductive Gap Pads

BENEFITS AND FEATURES

- High thermal performance
- Ultra-soft
- High compressibility
- Excellent gap-filling capability
- Naturally tacky

OVERVIEW

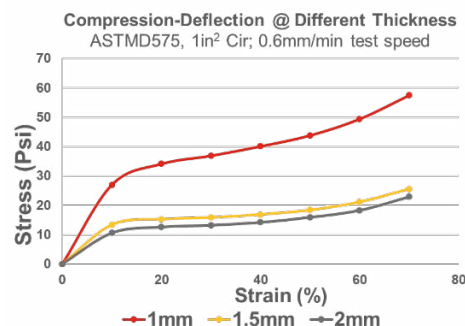
Honeywell TGP3500PT, TGP6000PT and TGP8000PT Thermally Conductive Gap Pads provide high thermal performance and excellent thermal reliability. The material's putty-like design enables excellent gap-filling capability for applications with large dimensional variances. Special surface reinforcement enables easier handling for operators during high volume assembly. The product is naturally tacky and requires no additional adhesive to mate to heat source and heat sink.

TYPICAL APPLICATIONS

- EV battery & charging station
- Automotive electronics
- Power devices & modules
- Telecommunications & network servers

STORAGE & USE

Shelf Life 12 months at 23±2°C



Property	TGP3500PT	TGP6000PT	TGP8000PT	Test Method
Color	White	Grey	Grey	Visual
Thickness (mm)*	0.5-5	1.0-5	1.0-5	ASTM D374
Specific Gravity	3.2	3.4	3.5	ASTM D792
Hardness (Shore00)	5	5	5	ASTM D2240
Thermal Conductivity (W/m·K)	3.5	6.0	8.0	ASTM D5470
Thermal Impedance (°C·in ² /W)(1mm@10psi) (Typical Value)	0.45	0.27	0.19	ASTM D5470
Dielectric Constant@1MHz	6.4	6.5	8.5	ASTM D150
Volume Resistivity (ohm·cm)	4 x 10 ¹³	4 x 10 ¹⁵	4 x 10 ¹⁵	ASTM D257
Flammability Rating	V-0	V-0	V-0	UL94

* Thickness range: with 0.25mm incremental
Thickness Tolerance: >=1mm, ±10%
0.5-1mm, ±0.1mm

Honeywell Electronic Materials

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Japan: 81-3-6730-7092
Korea: 82-2-3483-5076
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